

## Assembly of Integrated Circuits from Pyramid Semiconductor

Pyramid Semiconductor has established a brand new facility for assembly of monolithic Ceramic products and Multi-Chip Modules. **Pyramid Semiconductor is offering assembly services to its customers in this new facility.**



### Capabilities include:

- Monolithic Ceramic Products and Multi-Chip Modules
- Class 1000 Clean Room (Class 100 under Laminar Flow Hoods)
- Variety of Semiconductor Technologies: Bulk Silicon CMOS, SOS and Bipolar Products.
- Die Attach: JM7000 and Eutectic
- Wire bond: Aluminum
- Seal: Solder sealing
- Surface Mount Assembly
- Package Families:
  - ◆ Ceramic Side Brazed
  - ◆ Ceramic Top Brazed
  - ◆ Surface Mount LCC
  - ◆ Quad Flat Pack (QFP)
  - ◆ Pin Grid Array (PGA)
  - ◆ J-Bend Ceramic
  - ◆ Multi-Chip Modules



Assembly of the products can be performed on a quick engineering assembly mode or to the full MIL-STD-883 Assembly mode for Class B and Class S (Space) Levels. Certificate of Conformance to MIL-STD-883 will be provided. Die Shear (Test Method 2019) and Bond Pull (Test Method 2011) are performed on all Lots as well as High Magnification Visual (> 100X Test Method 2010).



### Additional services offered as part of an assembly requirement include:

- Ink Marking of products as well as Mark Permanency tests (Test Method 2015) with issuance of a Certificate of Conformance.
- Fine and Gross Leak testing (Test Method 1014).
- Dynamic Burn-In.

**Pyramid Semiconductor** is committed to fast turn assembly requirements providing excellent quality, complete documentation for traceability available for review, and perfect customer service.